

Epoxy Resin Composition

ABSTRACT

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The present invention relates to an epoxy resin compound useful for encapsulating electronic devices comprising the following components: (A) an epoxy resin whereby 25 – 75 wt % of the epoxy resin is of multi aromatic type and the balance of the epoxy resin is made up by one or more epoxy resin
10 selected from the group comprising ortho-cresol novolac epoxy resin, epoxy resin of dicyclo-pentadiene type, epoxy resin of biphenyl type, epoxy resin of bisphenol type and a combination thereof; (B) a phenolic resin curing agent whereby 25 – 75 wt % of the phenolic resin curing agent is made up by paraxylene-modified phenolic resin and the balance of the phenolic resin
15 curing agent is of multi aromatic type; (C) an inorganic filler; and (D) a curing accelerator.